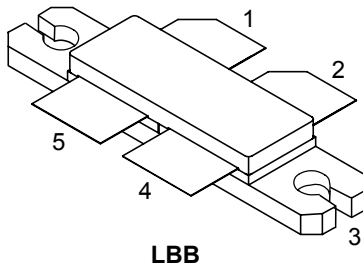


150 W, 28/32 V RF power LDMOS transistor from HF to 1 GHz



Pin connection	
Pin	Connection
1	Drain A
2	Drain B
3	Source (bottom side)
4	Gate B
5	Gate A



Product status link	
RF3L05150CB4	

Product summary	
Order code	RF3L05150CB4
Marking	RF3L05150CB4
Package	LBB
Packing	Tape and reel 13"
Base/bulk quantity	100/100

Features

Order code	Frequency	V _{DD}	P _{OUT}	Gain	Efficiency
RF3L05150CB4	520 MHz	28 V	150 W	23 dB	60 %

- High efficiency and linear gain operations
- Integrated ESD protection
- Large positive and negative gate-source voltage range for improved class C operation
- In compliance with the european directive 2002/95/EC

Applications

- 2-30 MHz HF or short wave communication
- 30-88 MHz ground communication
- 118-140 MHz Avionics
- 136-174 MHz commercial ground communication
- 30-512 MHz Jammer, ground/air communication
- HF to 1000 MHz ISM - instrumentation

Description

The RF3L05150CB4 is a 150 W, 28/32 V LDMOS FET designed for wide-band communication and ISM applications with frequencies from HF to 1 GHz. It can be used in class AB, B or C for all typical modulation formats.

1 Electrical ratings

Table 1. Absolute maximum ratings ($T_C = 25\text{ °C}$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	90	V
V_{GS}	Gate-source voltage	-8 to 10	V
V_{DD}	Maximum operating voltage	36	V
T_{STG}	Storage temperature range	-65 to 150	°C
T_J	Maximum junction temperature	200	°C

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{THJC}^{(1)}$	Junction-case thermal resistance	0.4	°C/W

1. $T_C = 85\text{ °C}$, $T_J = 200\text{ °C}$, DC test.

Table 3. ESD protection

Symbol	Test methodology	Class
HBM	Human body model (per JESD22-A114)	2

2 Electrical characteristics

($T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Table 4. Static

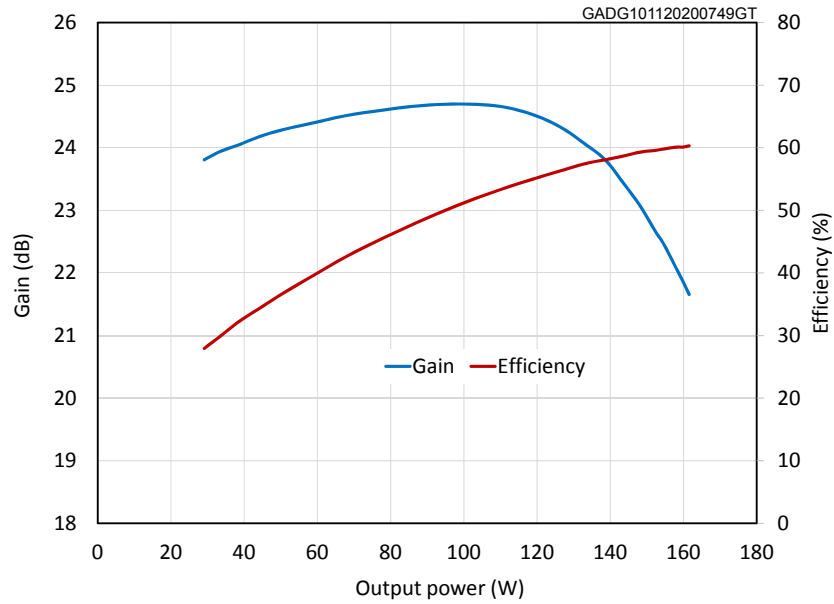
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_{DS} = 100\text{ }\mu\text{A}$	90			V
I_{DSS}	Zero gate voltage drain leakage current	$V_{GS} = 0\text{ V}, V_{DS} = 75\text{ V}$			1	μA
I_{GSS}	Gate-source leakage current	$V_{GS} = 10\text{ V}, V_{DS} = 0\text{ V}$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = 42\text{ V}, I_{DS} = 600\text{ }\mu\text{A}$	1.75		2.50	V
$V_{GS(Q)}$	Gate quiescent voltage	$V_{DS} = 1\text{ V}, I_{DS} = 800\text{ mA}$	2.0	3.8	5.0	V
$V_{DS(on)}$	Static drain-source on-voltage	$V_{GS} = 10\text{ V}, I_{DS} = 2\text{ A}$			650	mV
$I_{DS(on)}$	Static drain-source on-current	$V_{GS} = 10\text{ V}, V_{DS} = 100\text{ mV}$			2.5	A
$R_{DS(on)}$	Drain-source on-state resistance	$V_{GS} = 10\text{ V}, V_{DS} = 100\text{ mV}$			1	Ω
C_{ISS}	Common source input capacitance			70		pF
C_{RSS}	Common source feedback capacitance	$V_{GS} = 0\text{ V}, V_{DD} = 28\text{ V},$ $f = 1\text{ MHz}$		1.1		pF
C_{OSS}	Common source output capacitance			30		pF

Table 5. Dynamic

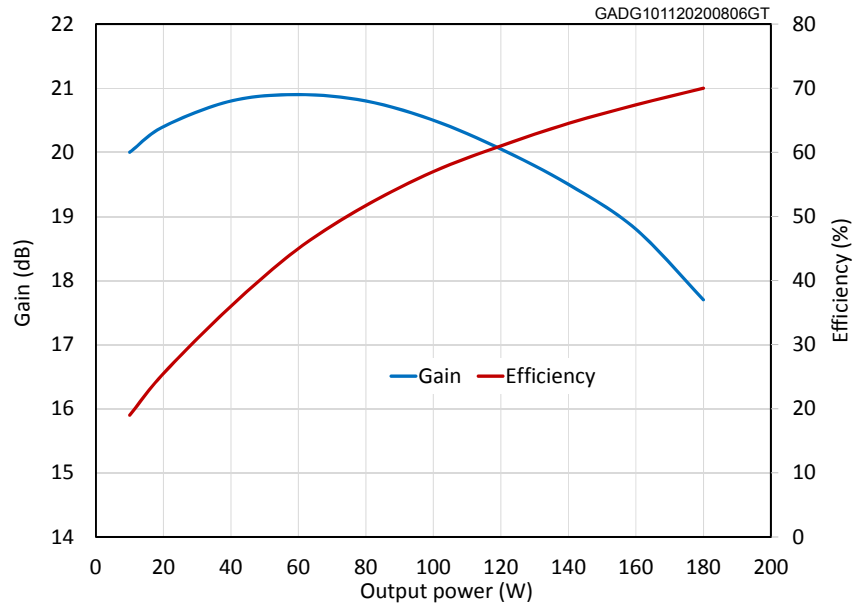
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
f	Frequency				1000	MHz
P_{OUT}	Output power			150		W
G_{PS}	Power gain	f = 520 MHz		23		dB
η_D	Drain efficiency			60		%
VSWR	Load mismatch	At 150 W pulsed CW output power, all phase angles			20:1	

Note: $V_{DD} = 28\text{ V}, I_{DQ} = 500\text{ mA},$ pulse width = 20 $\mu\text{s},$ duty cycle = 10%.

3 Typical performances

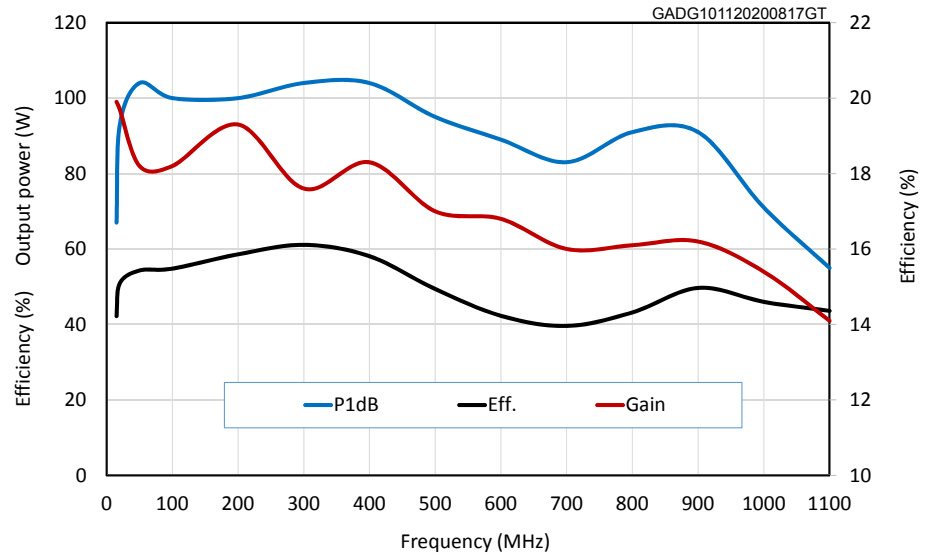
Figure 1. Power gain and drain efficiency versus output power (f = 520 MHz)


Note: $V_{DD} = 28\text{ V}$, $I_{DQ} = 500\text{ mA}$, pulse width = 20 μs , duty cycle = 10%.

Figure 2. Power gain and drain efficiency versus output power (f = 860 MHz)


Note: $V_{DD} = 32\text{ V}$, $I_{DQ} = 400\text{ mA}$, pulse width = 20 μs , duty cycle = 10%.

Figure 3. Gain, efficiency and output power versus frequency (typical broadband data)



Note: $V_{DD} = 28\text{ V}$, $I_{DQ} = 400\text{ mA}$, pulse width = 20 μs , duty cycle = 10%.

4 Test circuit (f = 650 MHz)

Figure 4. Test circuit layout

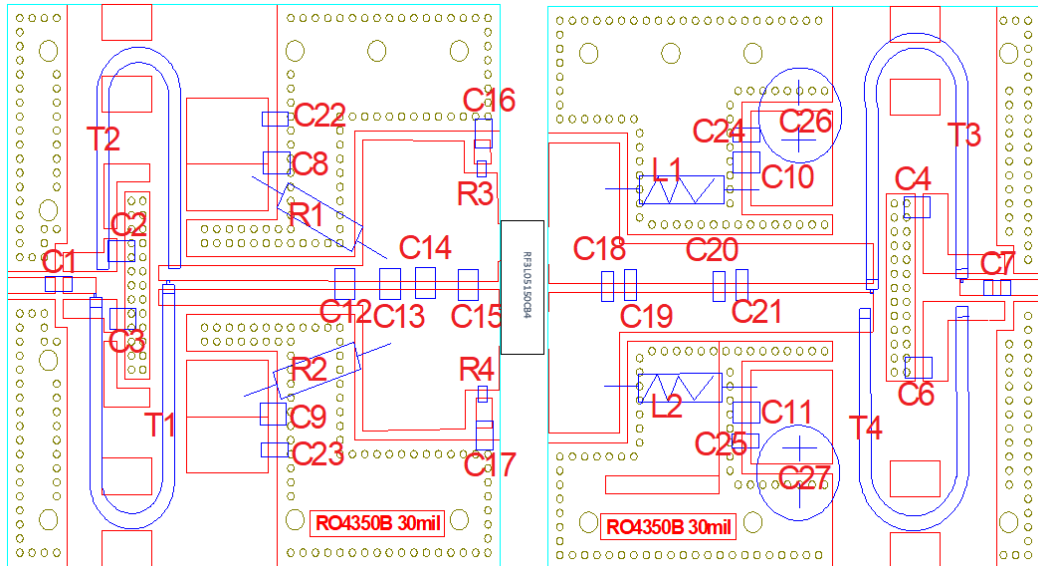


Figure 5. Test circuit photo

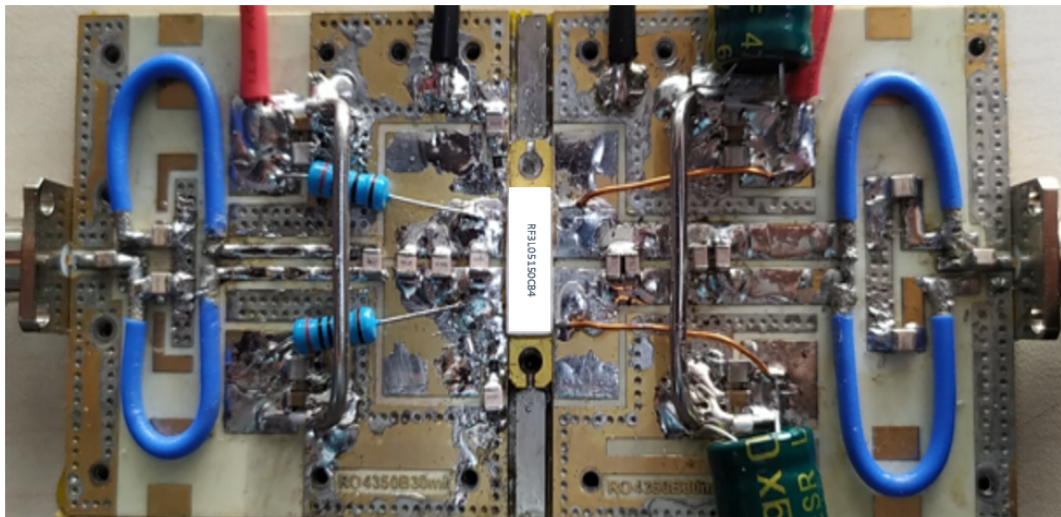


Table 6. Components list

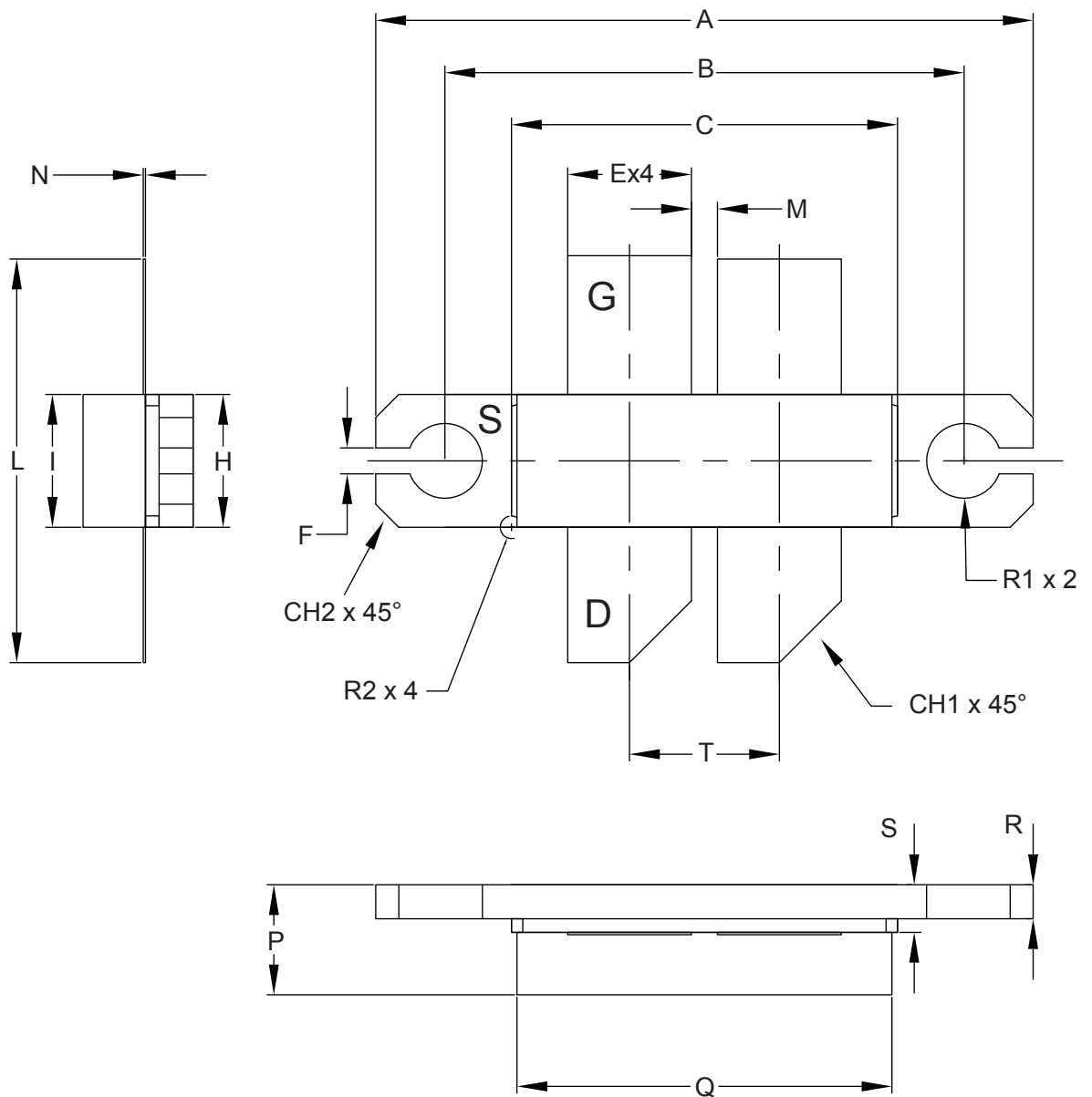
Component	Value	Order code
C1~C7	47 pF	DLC70B
C8~C11	68 pF	ATC800B
C12,C13,14	18 pF	DLC70B
C15	20 pF	DLC70B
C16,C17	1000 pF	DLC70B
C18	2.2 pF	DLC70B
C19	5.6 pF	DLC70B
C20	12 pF	DLC70B
C21	5.6 pF	DLC70B
C22~C25	110 μ F	100V/10 μ F
C26,C27	470 μ F	63V/470 μ F
R1,R2	200 Ω	
R3,R4	Chip resistor, 15 Ω , 0805	
L1,L2	ϕ 0.5, 30 mm, enameled wire	
T1,T2,T3,T4	25 Ω , 50 mm	SF-086-1.5
PCB	30mil Rogers4350B	

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

5.1 LBB package information

Figure 6. LBB package outline



DM00666717_2

Table 7. LBB mechanical data

Symbol	Millimeters		
	Min.	Typ.	Max.
A	28.82	28.95	29.08
B	22.73	22.86	22.99
C	16.87	17.00	17.13
E	5.32	5.45	5.58
F	1.01	1.14	1.27
H	5.72	5.85	5.98
I	5.72	5.85	5.98
L	17.65	17.78	17.91
M	1.02	1.15	1.28
N		0.10	
P	4.72	4.85	4.98
Q	16.38	16.51	16.64
R	1.37	1.50	1.63
S	1.97	2.10	2.23
T		6.60	
CH1		2.72	
CH2		1.02	
R1		1.65	
R2		0.50	

Revision history

Table 8. Document revision history

Date	Version	Changes
08-Jun-2020	1	First release
12-Nov-2020	2	Updated Features. Updated Table 5. Dynamic. Updated Section 3 Typical performances. Updated Section 4 Test circuit (f = 650 MHz). Minor text changes.

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